

WHAT IS CLAIMED IS:

1. A light emitting device comprising:

an insulating film over a substrate having a metallic surface;

a light emitting element on the insulating film;

said light emitting element including:

an anode;

a cathode;

an EL material interposed between the anode and the cathode.

2. A light emitting device comprising:

an insulating film over a substrate having a metallic surface;

a light emitting element on the insulating film;

said light emitting element including:

an anode;

a cathode;

an EL material interposed between the anode and the cathode,

wherein a light shielding film is formed in contact with the cathode, or
the light shielding film is formed through an insulating film or a conductive film.

3. A device according to claim 1,

wherein the substrate having the metallic surface is a heat resistive
metallic substrate.

4. A device according to claim 3,

wherein a thickness of the heat resistive metallic substrate is in a range
of 5 μm to 30 μm .

5. A device according to claim 1,
wherein a maximum surface roughness (Rmax) of the substrate is equal to or less than 1 μm .

6. A device according to claim 1,
wherein a radius of curvature of convex portions existing on a surface of the substrate is equal to or greater than 1 μm .

7. A device according to claim 1,
wherein the light emitting device is one selected from the group consisting of a video camera, a digital camera, a goggle-type display, a navigation system for vehicles, a personal computer, and a portable information terminal.

8. A method of manufacturing a light emitting device, said method comprising the steps of:

bending edge portions of a substrate having a metallic surface;
fixing the substrate to a substrate holder;
forming an insulating film over the substrate having the metallic surface;
forming a light emitting element on the insulating film; and
separating the substrate from the substrate holder.

9. A method according to claim 8,
wherein the fixing step is performed within a vacuum.

10. A method according to claim 8,
wherein the fixing step is performed at a temperature in a range of room

temperature to 400°C.

11. A method according to claim 8,
wherein edge portions of the substrate holder have curvature.

12. A method according to claim 8,
wherein the substrate holder has a same thermal expansion coefficient
as the substrate having the metallic surface.

13. A method according to claim 8,
wherein the substrate having the metallic surface is a heat resistive
metallic substrate.

14. A method according to claim 8,
wherein a thickness of the heat resistant metallic substrate is in a range
of 5 μm to 30 μm .

15. A method according to claim 8,
wherein the substrate holder comprises one selected from the group
consisting of stainless steel, ceramic and Al_2O_3 .

16. A method according to claim 8,
wherein the substrate holder has a thickness in a range of 500 μm to
1000 μm .

17. A device according to claim 2,
wherein the substrate having the metallic surface is a heat resistive

metallic substrate.

18. A device according to claim 17,
wherein a thickness of the heat resistive metallic substrate is in a range
of 5 μm to 30 μm .

5 19. A device according to claim 2,
wherein a maximum surface roughness (R_{max}) of the substrate is equal
to or less than 1 μm .

20. A device according to claim 2,
wherein a radius of curvature of convex portions existing on a surface of
10 the substrate is equal to or greater than 1 μm .

21. A device according to claim 2,
wherein the light emitting device is one selected from the group
consisting of a video camera, a digital camera, a goggle-type display, a navigation
system for vehicles, a personal computer, and a portable information terminal.